

PATENT ASSIGNMENT

Electronic Version v1.1
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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
LEI LI	10/20/2010
RECEIVING PARTY DATA	
Name:	HONG FU JIN PRECISION INDUSTRY (ShenZhen) CO., LTD.
Street Address:	No. 2, 2nd Donghuan Road, Longhua Town, Bao' an District
City:	Shenzhen City, Guangdong Province
State/Country:	CHINA
Name:	HON HAI PRECISION INDUSTRY CO., LTD.
Street Address:	66, CHUNG SHAN ROAD
City:	Tu-Cheng, Taipei Hsien
State/Country:	TAIWAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12911845
CORRESPONDENCE DATA	
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ATTORNEY DOCKET NUMBER:	US34223
NAME OF SUBMITTER:	Steven M. Reiss

CH \$40.00 12911845

Total Attachments: 2

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ASSIGNMENT

In consideration of value received, the receipt and sufficiency of which are hereby acknowledged, the undersigned ASSIGNOR(S)

- 1. LEI LI , residing at Shenzhen, Guangdong, China
- 2. _____ , residing at _____
- 3. _____ , residing at _____
- 4. _____ , residing at _____
- 5. _____ , residing at _____
- 6. _____ , residing at _____
- 7. _____ , residing at _____
- 8. _____ , residing at _____

hereby sell(s), assign(s) and transfer(s) unto: **HONG FU JIN PRECISION INDUSTRY (SHENZHEN) CO., LTD.** having a principal place of business at **No. 2, 2nd Donghuan Road, Longhua Town, Bao'an District, Shenzhen City, Guangdong Province 518109, P.R.C.** and **HON HAI PRECISION INDUSTRY CO., LTD.** having a principal place of business at **66, Chung Shan Road, Tu-Cheng City, Taipei Hsien, Taiwan, R.O.C.** hereafter designated "ASSIGNEE" the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100, in the invention and all patent applications including any and all divisions, continuations, substitutes, and reissues thereof, and all resulting patents, known as **CIRCUIT BOARD STRUCTURE FOR CIRCUIT BOARD MODULE** for which the undersigned

[] previously executed --- Ser. No. _____ and filing date of _____
[x] is executing concurrently herewith

an application for Letters Patent of United States of America

AND the undersigned hereby authorize(s) and request(s) the United States Commissioner of Patents and Trademarks to issue said Letters Patent to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree(s) that the attorneys of record in said application, if any, shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree(s) to testify and execute any papers for ASSIGNEE, its successors, assigns and legal representatives, deemed essential by ASSIGNEE to ASSIGNEE's full protection and title in and to the invention hereby transferred.

1.	<u>LEI LI</u> LEILI	<u>Oct. 20, 2010</u> Date
2.	_____	_____ Date
3.	_____	_____ Date
4.	_____	_____ Date
5.	_____	_____ Date
6.	_____	_____ Date
7.	_____	_____ Date
8.	_____	_____ Date
9.	_____	_____ Date